ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® MAterial Compo © Copyright 2005. II international and Pan	PC, Bannock	burn, Illinois. A	ll rights reserved ur ntions.	nder both	This docume level parts, t	ent is a declar he declaratio	ration of the s	substances ses all lowe	within the ma r level materia	nufacturer l als for which	isted item. 1 the manu	Note: if t facturer h	he item is an as as engineering i	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Information															
Company name*			Company unique ID			Unique ID Authority					Response Date*				
onsemi											2023-06-08				
Contact Name Title			Fitle - Contact			Phone - Contact*				Er	Email - Contact*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA				P	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -			le - Representative			Phone - Representative*				Er	Email - Representative*				
Product-Env-Stewards		Product Envi	Product Enviro Compliance			NA				P	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iter	n Number	Mfr Item Name			Effective Da	ate Version	n 1	Manufacturing Site		Weig	ght*	UOM	Unit Type	
	NLV74 G	HC574ADTR2	OCTAL D-TYPE 3-STATE FF			2023-06-08]	PH1		69.2	8	mg	Each	
Manufacturing Proccess Informat	tion		-					·							
Terminal Plating / Grid Array Ma	terial	Terminal Base Alloy		-STD-020 MS	L Rating	Peak Pr	eak Process Body Temperatur		ure Max Time at Peak Temper		nperature	erature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1				260		C	30 seco		seconds	econds 3			
Comments															
evel 1 - maximum time at peak temperatu	re during so	oldering is 10-3	0 seconds												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.29	mg	Supplier	Silicon (Si)	7440-21-3		0.29	mg
Die Attach	2.46	mg		Epoxy resin	proprietary data		0.246	mg
			Supplier	Ethylene dimethacrylate	97-90-5		0.123	mg
			Supplier	Silver (Ag)	7440-22-4		1.968	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.123	mg
Lead Frame	38.58	mg	Supplier	Iron (Fe)	7439-89-6		0.733	mg
			Supplier	Copper (Cu)	7440-50-8		37.847	mg
Mold Compound-Black	24.35	mg		Epoxy resin	proprietary data		1.2175	mg
			Supplier	Phenol Resin	Proprietary Data		0.974	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.435	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2435	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		19.48	mg
Plating	3.44	mg	Supplier	Palladium (Pd)	7440-05-3		0.2614	mg
			В	Nickel (Ni)	7440-02-0		3.1304	mg
			Supplier	Gold (Au)	7440-57-5		0.0482	mg
Wire Bond - Cu	0.16	mg	Supplier	Copper (Cu)	7440-50-8		0.16	mg